



I HEREBY CERTIFY THAT THE CORRESPONDENCE IS BEING
DEPOSITED WITH THE UNITED STATES POSTAL SERVICE AS
FIRST-CLASS MAIL IN AN ENVELOPE ADDRESSED TO:
ASSISTANT COMMISSIONER FOR PATENTS, WASHINGTON, D.C. 20231
ON THIS 1ST DAY OF OCTOBER, 2001.

BY

Richard M. Bach

1714

A
#4/jm
10.11.01

1998/G 004 (5587*264)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

STEFAN DISCH ET AL

SERIAL NO: 09/647,743

FILED: OCTOBER 4, 2000

FOR: POLYOXYMETHYLENE MOULDING
MATERIAL WITH IMPROVED
PROCESSING STABILITY AND A
REDUCED EMISSIONS TENDENCY

ART UNIT: 1714

EXAMINER: HOKE, V.

Assistant Commissioner for Patents
Washington, DC 20231

RECEIVED
OCT 09 2001
TC 1700

Sir:

In response to the outstanding Office Action dated July 2, 2001, kindly amend the
above identified application as follows.

IN THE CLAIMS

Cancel claims 2, 3, and 5-10.

Amend claims 1 and 4 as follows.

A¹

1. A molding composition made from linear polyoxymethylene copolymers which
essentially have oxymethylene units and oxyethylene units as structural units in the
polymer chain, where the proportion of oxyethylene units in the structural units of the
polymer chain is from 1.5 to 2.5 mol% the molding composition having a formaldehyde
emission, measured on sheets of wall thickness 1 mm after 24 hours in storage, in